



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

# 22/P  
4/28/3  
Sunder

Applicants: **T. SATOH et al.**

Application No.: **09/809,181**

Filing Date: **March 16, 2001**

Title: **SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD  
FOR HIGH RELIABILITY AND PRODUCTION YIELD RATE WITH  
MINIMAL DAMAGE DUE TO APPLICATION OF MECHANICAL  
STRESS AND THERMAL STRESS (AS AMENDED)**

Art Unit: **2815**

Examiner: **Jose R. Diaz**

**AMENDMENT IN SUPPORT OF  
REQUEST FOR CONTINUED EXAMINATION (RCE)**

Assistant Commissioner for Patents  
Washington, D.C. 20231

**April 21, 2003**

Sir:

Pursuant to Applicants' earlier filed Notice of Appeal on October 21, 2002, and in response to the Advisory Action (Paper No. 17) dated on October 8, 2002, the following amendments and remarks are submitted in the above-identified application in favor of continued examination.

**IN THE CLAIMS**

**Please amend claims 1, 5 and 33, as follows:**

**1. (Currently Amended)** A semiconductor device comprising:

semiconductor elements obtained by cutting a semiconductor wafer having an integrated circuit and an electrode pad formed on one side along a cutting scribe line,